



YOUSHANG SEMICONDUCTOR

**设计研发新型功率器件**

**各类小信号开关**

**中低压及高压大电流等场效应管**

0755-83047638

ysbdt@szyoushang.cn

www.szyoushang.cn



企业微信二维码



企业QQ二维码

## Description

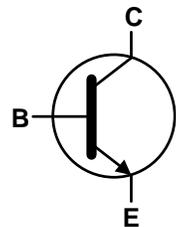
This bipolar junction transistor (BJT) is designed to meet the stringent requirements of Automotive Applications.

## Features

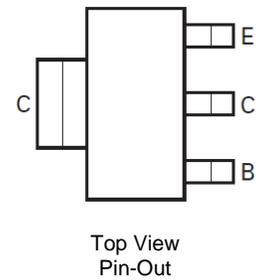
- $BV_{CE0} > 75V$
- $I_C = 4.5A$  High Continuous Collector Current
- $I_{CM} = 10A$  Peak Pulse Current
- Low Saturation Voltage  $V_{CE(sat)} < 120mV @ 1A$
- $h_{FE} > 300 @ I_C = 1A$  for a High Gain Hold-Up
- $R_{CE(sat)} = 78m\Omega$  at 4.5A for a Low Equivalent On-Resistance

## Mechanical Data

- Case: SOT223
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish—Matte Tin Plated Leads. Solderable per MIL-STD-202, Method 208 <sup>Ⓔ</sup>
- Weight: 0.112 grams (Approximate)



Device Symbol



**Absolute Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V <sub>CBO</sub>	150	V
Collector-Emitter Voltage	V <sub>CEO</sub>	75	V
Emitter-Base Voltage	V <sub>EBO</sub>	7	V
Continuous Collector Current	I <sub>C</sub>	4.5	A
Continuous Base Current	I <sub>B</sub>	500	mA
Peak Pulse Collector Current	I <sub>CM</sub>	10	A

**Thermal Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

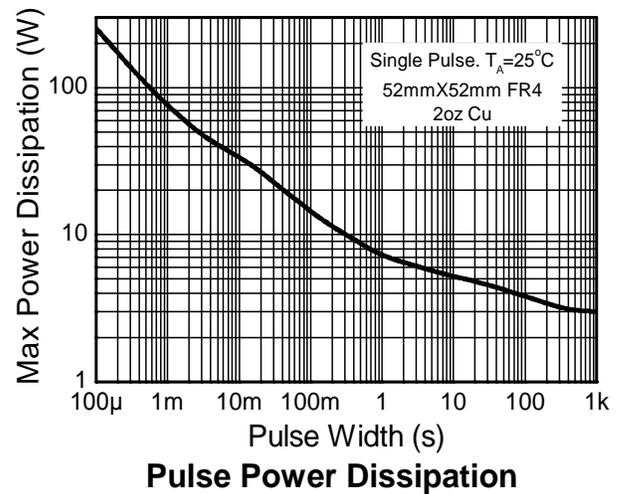
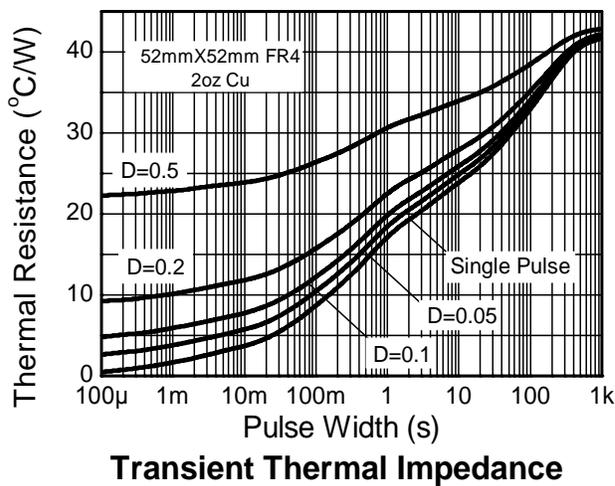
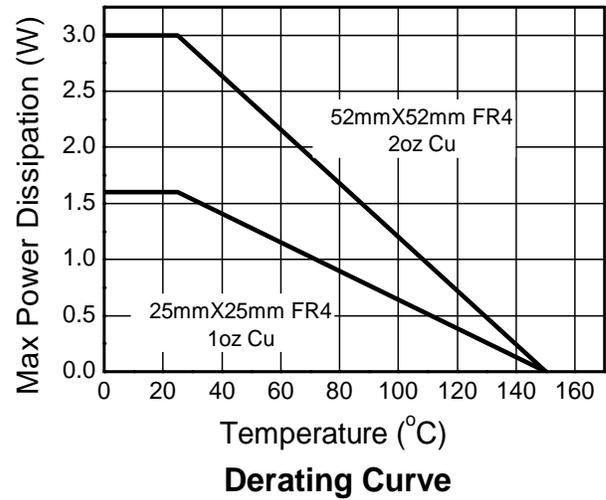
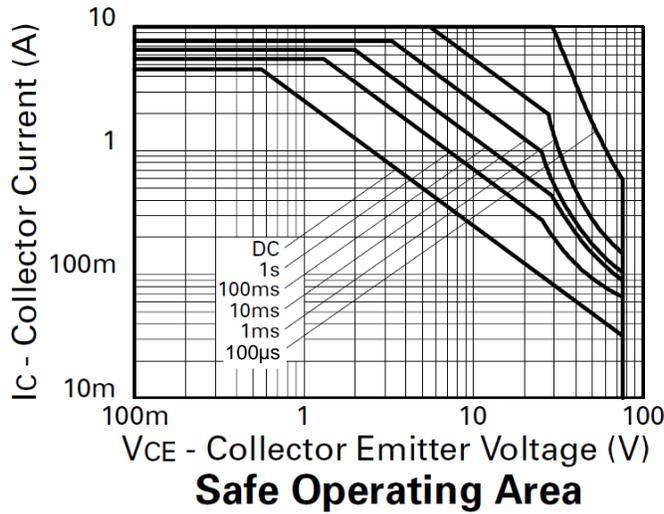
Characteristic	Symbol	Value	Unit
Power Dissipation	(Note 6)	3.0	W
	(Note 7)	2.0	
	(Note 8)	1.6	
	(Note 9)	1.2	
Thermal Resistance, Junction to Ambient	(Note 6)	41.7	°C/W
	(Note 7)	62.5	
	(Note 8)	78.1	
	(Note 9)	104	
Thermal Resistance Junction to Lead	(Note 10) R <sub>θJL</sub>	10.9	
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

**ESD Ratings** (Note 11)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge—Human Body Model	ESD HBM	4000	V	3A
Electrostatic Discharge—Machine Model	ESD MM	400	V	C

- Notes:
6. For a device mounted with the collector lead on 52mm x 52mm 2oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still air conditions whilst operating in a steady-state.
  7. Same as Note 6, except the device is mounted on 25mm x 25mm 2oz copper.
  8. Same as Note 6, except the device is mounted on 25mm x 25mm 1oz copper.
  9. Same as Note 6, except the device is mounted on minimum recommended pad layout.
  10. Thermal resistance from junction to solder-point (at the end of the collector lead).
  11. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

### Thermal Characteristics and Derating Information

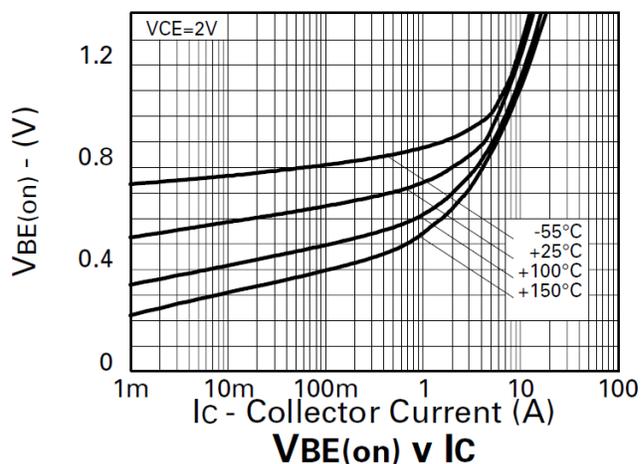
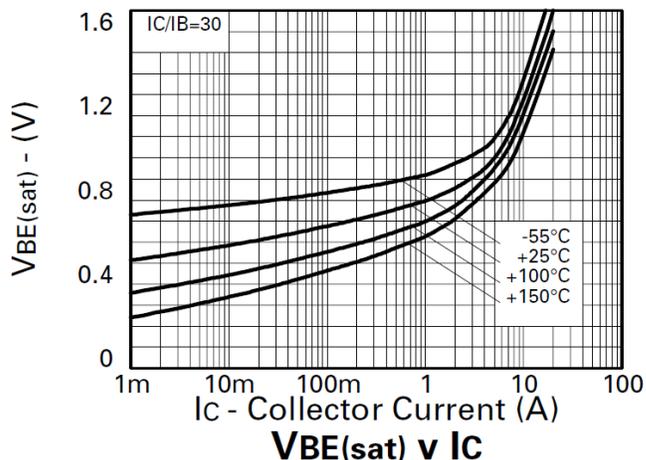
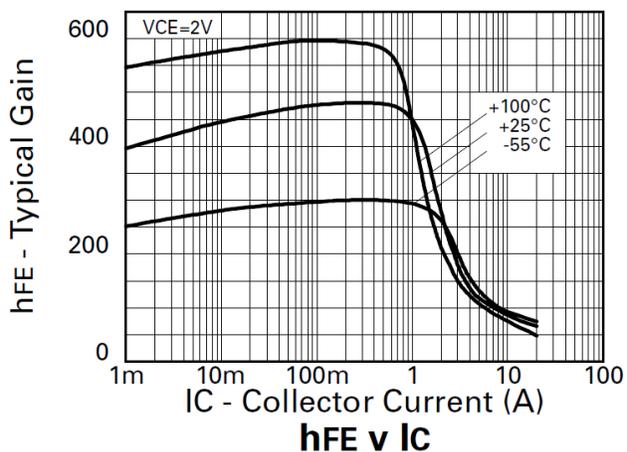
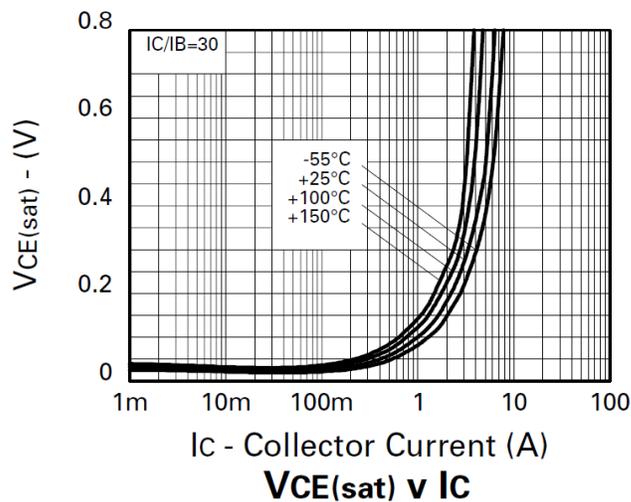
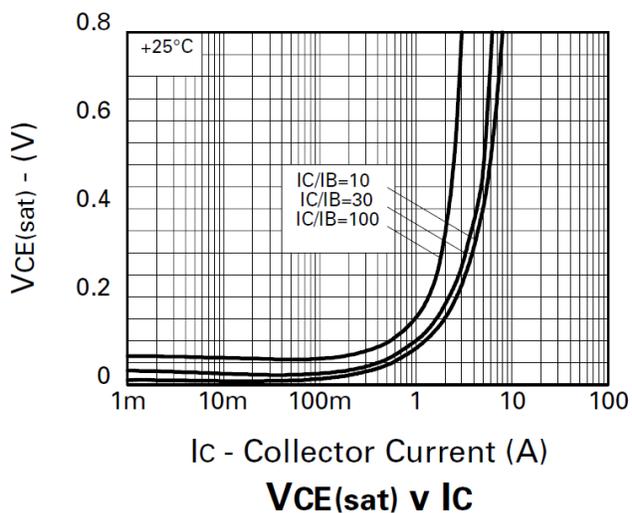


**Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV <sub>CBO</sub>	150	250	—	V	I <sub>C</sub> = 100μA
Collector-Emitter Breakdown Voltage	BV <sub>CES</sub>	150	250	—	V	I <sub>C</sub> = 100μA
Collector-Emitter Breakdown Voltage (Note 12)	BV <sub>CEO</sub>	75	100	—	V	I <sub>C</sub> = 10mA
Collector-Emitter Breakdown Voltage	BV <sub>CEV</sub>	150	250	—	V	I <sub>C</sub> = 100μA, V <sub>EB</sub> = 1V
Emitter-Base Breakdown Voltage	BV <sub>EBO</sub>	7.0	8.8	—	V	I <sub>E</sub> = 100μA
Collector Cutoff Current	I <sub>CBO</sub>	—	0.9	10	nA	V <sub>CB</sub> = 120V
Collector Cutoff Current	I <sub>CES</sub>	—	1.5	10	nA	V <sub>CES</sub> = 120V
Emitter Cutoff Current	I <sub>EBO</sub>	—	0.3	10	nA	V <sub>EB</sub> = 4V
DC Current Transfer Static Ratio (Note 12)	h <sub>FE</sub>	270	440	—	—	I <sub>C</sub> = 10mA, V <sub>CE</sub> = 2V
		300	450	1,200		I <sub>C</sub> = 0.5A, V <sub>CE</sub> = 2V
		300	450	—		I <sub>C</sub> = 1A, V <sub>CE</sub> = 2V
		40	60	—		I <sub>C</sub> = 4.5A, V <sub>CE</sub> = 2V
		—	20	—		I <sub>C</sub> = 10A, V <sub>CE</sub> = 2V
Collector-Emitter Saturation Voltage (Note 12)	V <sub>CE(sat)</sub>	—	21	30	mV	I <sub>C</sub> = 0.2A, I <sub>B</sub> = 20mA
		—	55	75		I <sub>C</sub> = 0.5A, I <sub>B</sub> = 20mA
		—	150	200		I <sub>C</sub> = 1A, I <sub>B</sub> = 10mA
		—	160	210		I <sub>C</sub> = 2A, I <sub>B</sub> = 100mA
		—	350	440		I <sub>C</sub> = 4.5A, I <sub>B</sub> = 200mA
Base-Emitter Saturation Voltage (Note 12)	V <sub>BE(sat)</sub>	—	900	1,000	mV	I <sub>C</sub> = 3A, I <sub>B</sub> = 100mA
Base-Emitter Turn-On Voltage (Note 12)	V <sub>BE(on)</sub>	—	825	950	mV	I <sub>C</sub> = 3A, V <sub>CE</sub> = 2V
Transitional Frequency (Note 12)	f <sub>T</sub>	—	140	—	MHz	I <sub>C</sub> = 50mA, V <sub>CE</sub> = 10V, f = 100MHz
Output Capacitance	C <sub>obo</sub>	—	21	30	pF	V <sub>CB</sub> = 10V, f = 1MHz
Switching Time	t <sub>on</sub>	—	162	—	ns	V <sub>CC</sub> = 50V, I <sub>C</sub> = 2A,
	t <sub>off</sub>	—	900	—	ns	I <sub>B1</sub> = I <sub>B2</sub> = ±20mA

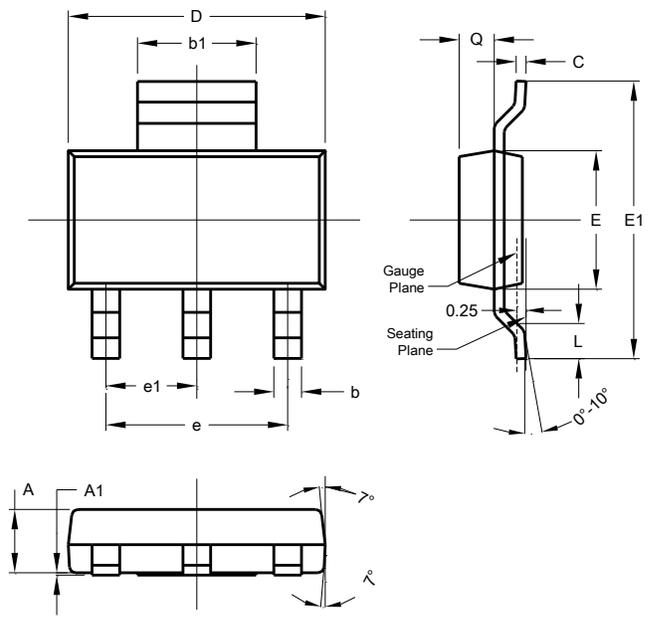
Note: 12. Measured under pulsed conditions. Pulse width ≤ 300μs. Duty cycle ≤ 2%.

**Typical Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)



### Package Outline Dimensions

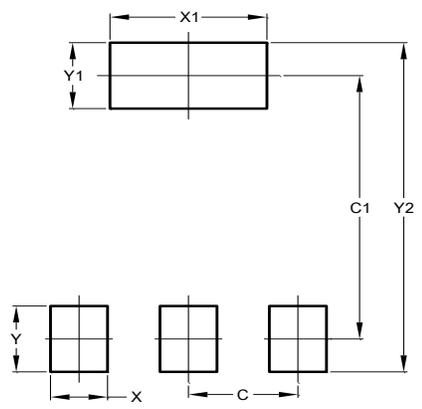
SOT223



SOT223			
Dim	Min	Max	Typ
A	1.55	1.65	1.60
A1	0.010	0.15	0.05
b	0.60	0.80	0.70
b1	2.90	3.10	3.00
C	0.20	0.30	0.25
D	6.45	6.55	6.50
E	3.45	3.55	3.50
E1	6.90	7.10	7.00
e	-	-	4.60
e1	-	-	2.30
L	0.85	1.05	0.95
Q	0.84	0.94	0.89
All Dimensions in mm			

### Suggested Pad Layout

SOT223



Dimensions	Value (in mm)
C	2.30
C1	6.40
X	1.20
X1	3.30
Y	1.60
Y1	1.60
Y2	8.00